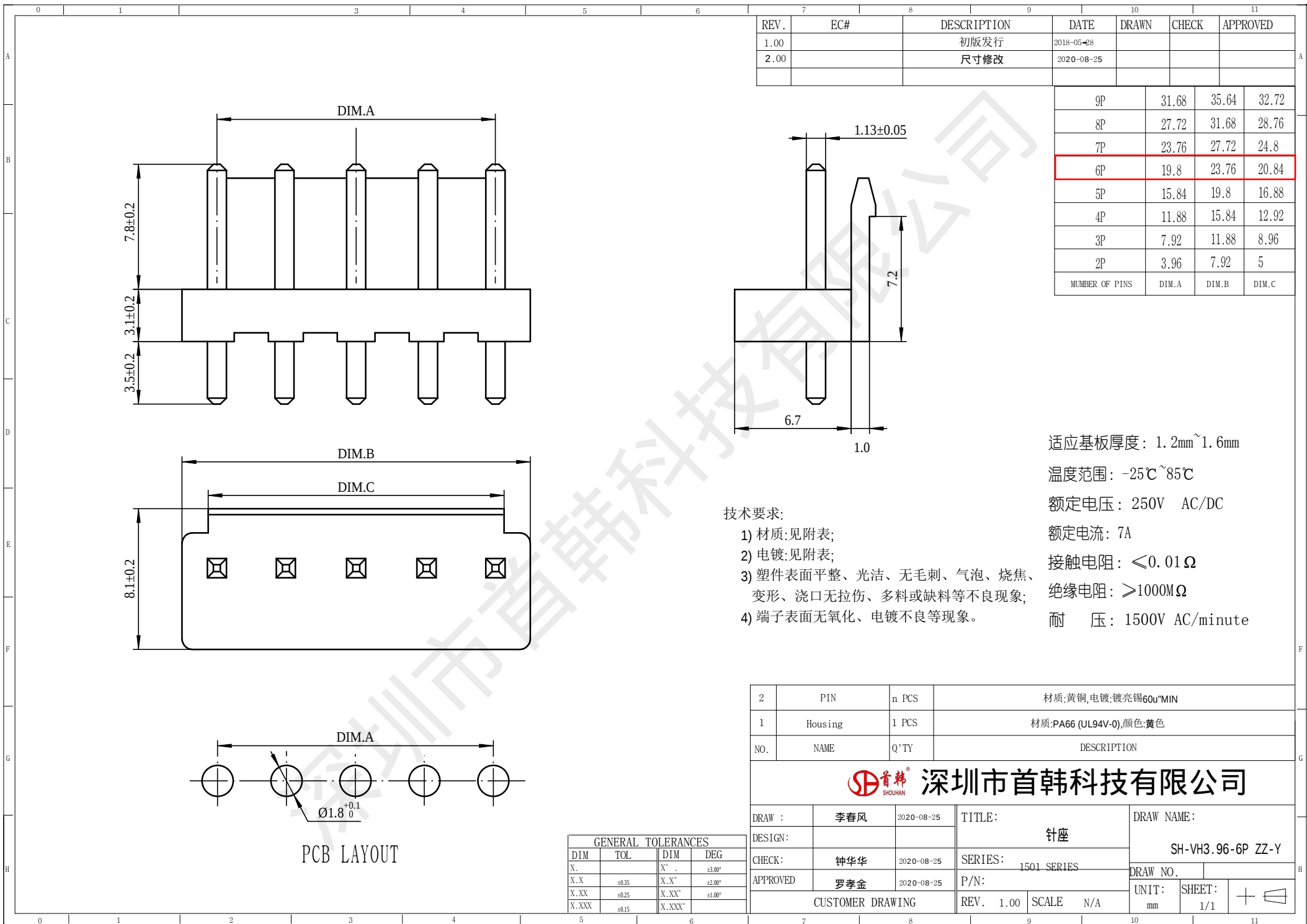






深圳市首韩科技有限公司

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## 承 认 书

### SPECIFICATION FOR APPROVAL

产 品 编 码

Material code:

产品名称 Project:

针座

规格型号 Part No:

SH-VH3.96-6P ZZ-Y

贵公司承认印 Approval signatures

| 料 号/Part No. | 签 章/Signatures |
|--------------|----------------|
|              |                |

日期 Date:

|             |     |  |
|-------------|-----|--|
| 拟制/Drawn    | 李春风 |  |
| 审核/Check    | 钟华华 |  |
| 批准/Approved | 罗孝金 |  |

## 1、SCOPE: (适用范围)

1.1 This specification covers production and inspection of Connector.

本规范内容适用于本公司普通系列型条形连接器（针座）产品的生产与检验。

## 2、USE CONDITION: (使用条件)

2.1 Ambient temperature Range:-25℃~+85℃

环境温度：-25℃~+85℃

2.2 Applicable PC board thickness:1.2~1.6mm

适用 PC 板厚度：1.2~1.6 mm

## 3、Appearance and Dimension: (外观及尺寸)

3.1 Appearance:Product surface without defect、dirt、crack、and mechanical damang,  
Contact without rust,plating not oxided and not peeled.

产品表面不应有对制品有害的缺陷、污垢、裂痕及机械损伤；接触件无锈蚀、镀层氧化、脱落等现象。

3.2 Dimension:According to drawings

外形尺寸：依照附图

3.3 Exchangable:Exchangable with same specification products.

互换性：相同规格应能互换

## 4、Material:

材 料 （以图纸为准）

| P/N<br>零件名称                   | Type<br>类 型        | Material<br>材 料                  | Finish<br>表面处理                         | Expiain<br>说 明     |
|-------------------------------|--------------------|----------------------------------|----------------------------------------|--------------------|
| Terminal<br>端子                | Contact<br>插 簧     | Phosphor bronze<br>锡青磷铜 厚 0.15mm | Tin Plating:3~4 μ m<br>镀锡：3~4 μ m      | RoHS<br>Comp liant |
| Housing<br>孔 座                | Plastic<br>塑 壳     | Nylon66 UL94V-0                  | Color:White<br>颜色：白色                   |                    |
| OpeningWafer<br>开口针座          | Contact<br>插 针     | Phosphor bronze<br>锡青磷铜 厚 0.30mm | Tin Plating:3~4 μ m<br>镀锡：3~4 μ m      |                    |
|                               | Plastic<br>塑 壳     | Nylon46 UL94V-0                  | Color: Beige<br>颜色：米色                  |                    |
| Lips Wafer<br>闭口针座            | Contact<br>插 针     | Phosphor bronze<br>锡青磷铜 厚 0.30mm | Gold Plating:3~4 μ " m<br>镀金：3~4 μ " m |                    |
|                               | Plastic<br>塑 壳     | PBT UL94V-0                      | Color: White<br>颜色：白色                  |                    |
| Tiepian Wafer<br>卧贴针座<br>立贴针座 | Contact<br>插 针     | Phosphor bronze<br>锡青磷铜 厚 0.30mm | Tin Plating:3~4 μ m<br>镀锡：3~4 μ m      |                    |
|                               | Solder tabs<br>焊护耳 | Phosphor bronze<br>锡青磷铜 厚 0.25mm | Tin Plating:3~4 μ m<br>镀锡：3~4 μ m      |                    |
|                               | Plastic<br>塑 壳     | Nylon46 UL94V-0                  | Color: Beige<br>颜色：米色                  |                    |

**5、Electrical Performance:**

## 电气性能

| NO.<br>序号 | Item<br>项目                    | Requirement<br>技术要求            |
|-----------|-------------------------------|--------------------------------|
| 5.1       | Voltage Rated<br>额定电压         | 250V AC DC                     |
| 5.2       | Current Rated<br>额定电流         | 7A AC DC                       |
| 5.3       | Contact Resistance<br>接触电阻    | $\leq 10\text{ m}\Omega$       |
| 5.4       | Insulation Resistance<br>绝缘电阻 | $\geq 1000\text{ M}\Omega$     |
| 5.5       | Dielectric Strength<br>耐压     | $\geq 1500\text{ V AC/minute}$ |

**6、Mechanical Performance:**

## 机械性能

| NO.<br>序号 | Item<br>项目                               | Requirement<br>技术要求         |
|-----------|------------------------------------------|-----------------------------|
| 6.1       | Male contact Retention force<br>PIN 针固定力 | $\geq 10\text{ N}$ per pin  |
| 6.2       | Female contact Retention force<br>端子固定力  | $\geq 10\text{ N}$ per pin  |
| 6.3       | Plug-in force<br>插入力                     | $\leq 3\text{ N}$ per pin   |
| 6.4       | Plug-out force<br>拔出力                    | $\geq 0.5\text{ N}$ per pin |

**7、Endurance Characteristics:**

## 环境性能

| NO.<br>序号 | Item<br>项目                           | Requirement<br>技术要求                                                                                                                                                                 |
|-----------|--------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 7.1       | Soldering test<br>可焊性                | Time: $2.5 \pm 0.5\text{ S}$ 时间: $2.5 \pm 0.5\text{ S}$<br>Temperature: $230 \pm 5^\circ\text{C}$ 温度: $230 \pm 5^\circ\text{C}$<br>Area of Soldering: $\geq 95\%$ 焊锡面积: $\geq 95\%$ |
| 7.2       | Resistance to soldering Heat<br>耐焊接热 | Time: $5 \pm 1\text{ S}$ 时间: $5 \pm 1\text{ S}$<br>Temperature: $230 \pm 5^\circ\text{C}$ 温度: $230 \pm 5^\circ\text{C}$<br>Appearance: NO Damage 外观: 无损坏                            |

|     |                                 |                                                                                                                                                                                                                                                                                                                                                              |
|-----|---------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 7.3 | Heat test<br>耐热性                | Time:96h 时间: 96 小时<br>Temperature:+85±3℃ 温度: +85±3℃<br>Appearance:NO Damage 外观: 无损坏<br>Contact resistance: ≤20 mΩ 接触电阻: ≤20 mΩ                                                                                                                                                                                                                               |
| 7.4 | Cold test<br>耐冷性                | Time:48h 时间: 48 小时<br>Temperature:-25±3℃ 温度: -25±3℃<br>Appearance:NO Damage 外观: 无损坏<br>Contact resistance: ≤20 mΩ 接触电阻: ≤20 mΩ                                                                                                                                                                                                                               |
| 7.5 | Temperature Cycling<br>温度循环     | Low temperature:-25±3℃ 低温: -25±3℃<br>High temperature:85±3℃ 高温: 85±3℃<br>For 5 cycles.test after keeping in Normal Condition for 30 min.<br>5 次循环后, 放置在正常环境中 30 分钟, 进行测试<br>Appearance: NO Damage 外观: 无损坏<br>Contact resistance: ≤20 mΩ 接触电阻: ≤20mΩ                                                                                                          |
| 7.6 | Invariab lenes humidity<br>恒定湿热 | Temperature:60±2℃ 温度: 60±2℃<br>Relative humidity:90%-96% RH<br>相对湿度: 90%-96% RH<br>Tim:96h 时间: 96 小时<br>Appearance:NO Damage 外观: 无损坏<br>Contact resistance: ≤20 mΩ 接触电阻: ≤20 mΩ<br>Insulation Resistance: ≥100MΩ 绝缘电阻: ≥100 MΩ                                                                                                                               |
| 7.7 | Salt Spray<br>盐雾试验              | Salt concentration: 5±1% 浓度: 5±1%<br>Temperature:35±2℃ 温度: 35±2℃<br>Tim:16±2h 时间: 16±2 小时<br>After salt is removed by running wafer and A drop is removed ,it is measured.<br>把试验样品从试验箱顶悬挂下来, 采用浓度 (5±1) %的 氯化钠溶液, 连续雾化 16 小时, 试验后用流动的蒸馏水 轻轻洗去表面沉积物, 在常温常驻湿条件下恢复 1-2 小时, 外观无损伤<br>Appearance:NO Damage 外观: 无损坏<br>Contact resistance: ≤20 mΩ<br>接触电阻: ≤20 mΩ |